Gap Pad® 2000S40

Highly Conformable, Thermally Conductive, Reinforced "S-Class" Gap Filling Material

Features and Benefits

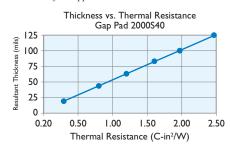
- Thermal conductivity: 2.0 W/m-K
- Low "S-Class" thermal resistance at very low pressures
- Highly conformable, low hardness
- Designed for low-stress applications
- Fiberglass reinforced for puncture, shear and tear resistance



Gap Pad 2000S40 is recommended for lowstress applications that require a mid to high thermally conductive interface material. The highly conformable nature of the material allows the pad to fill in air voids and air gaps between PC boards and heat sinks or metal chassis with stepped topography, rough surfaces and high stack-up tolerances.

Gap Pad 2000S40 is offered with inherent natural tack on both sides of the material allowing for stick-in-place characteristics during application assembly. The material is supplied with protective liners on both sides. The top side has reduced tack for ease of handling.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP PAD 2000S40					
OPERTY	IMPERIAL VALUE	METRIC VALUE		TEST METHOD	
or	Gray	Gray		Visual	
nforcement Carrier	Fiberglass	Fiberglass		_	
ckness (inch) / (mm)	0.020 to 0.125	0.508 to 3.175		ASTM D374	
erent Surface Tack (1 side)	2	2		_	
nsity (Bulk Rubber) (g/cc)	2.9	2.9		ASTM D792	
at Capacity (J/g-K)	0.6	0.6		ASTM E1269	
dness (Bulk Rubber) (Shore 00) (1)	30	30		ASTM D2240	
ing's Modulus (psi) / (kPa) (2)	45	310		ASTM D575	
ntinuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200		_	
CTRICAL					
lectric Breakdown Voltage (Vac)	>5000	>5000		ASTM D149	
lectric Constant (1000 Hz)	6.0	6.0		ASTM D150	
ume Resistivity (Ohm-meter)	1011	1011		ASTM D257	
ne Rating	V-O	V-O		U.L. 94	
ERMAL					
ermal Conductivity (W/m-K)	2.0	2.0		ASTM D5470	
THERMAL PERFORMANCE vs. STRAIN					
	Deflection (% strain)		10	20	30
Thermal Impedance (°C-in²/W) 0.040" (3)			0.97	0.89	0.80
Deflection (% strain)				0.89	- e

1) Thirty second delay value Shore 00 hardness scale. 2) Young's Modulus, calculated using 0.01 in/min. step rate of strair with a sample size of 0.79 inch². 3) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

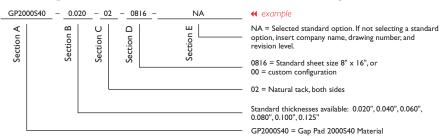
Typical Applications Include:

- Power electronics DC/DC; 1/4, 1/2, full bricks, etc.
- Mass storage devices
- Graphics card/processor/ASIC
- Wireline/wireless communications hardware
- Automotive engine/transmission controls

Configurations Available:

• Sheet form and die-cut parts

Building a Part Number



Note: To build a part number, visit our website at www.bergquistcompany.com.



Standard Options